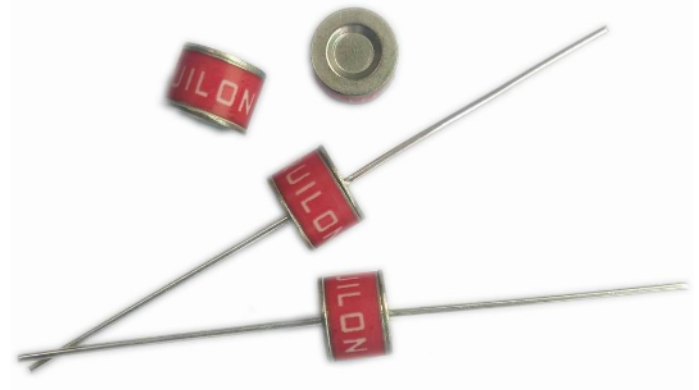


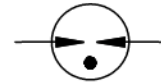
Description

2R-8 Gas Discharge Tubes (GDT) series provides high levels of protection against fast rising transients caused by lightning disturbances. Offered in a miniature surface mount package, it has a surge rating of 10KA/5KA/3KA 8/20 μ s.

2R-8 GDTs are high voltage (1000-5000V) components designed for surge protection and high isolation applications. It is also suitable for applications for which bias voltage or signal levels of several hundred volts are normally present. 2R-8 GDTs can be used in conjunction with MOVs (Metal Oxide Varistors) to provide superior protection performance for AC applications.



Electrical symbol



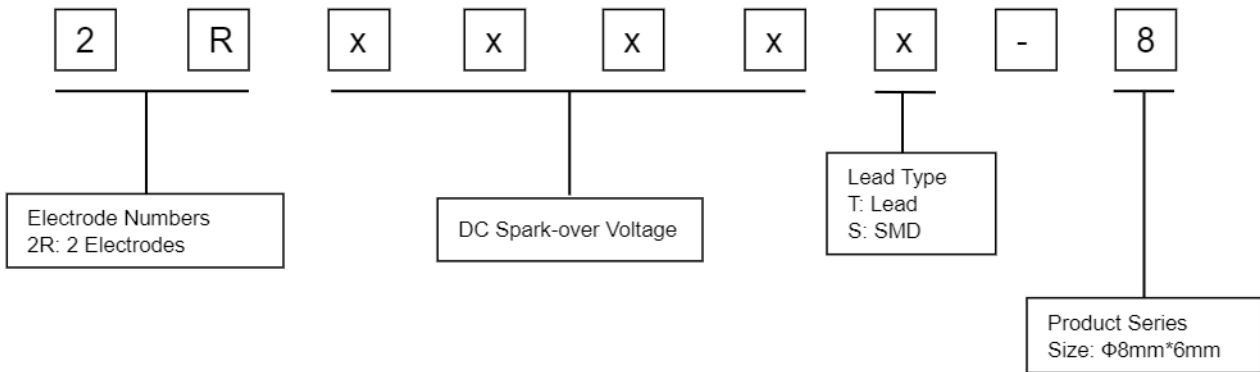
Features

- Voltage Ranges 1000V to 5000V
- Excellent response to fast rising transients
- 8/20 μ s Impulse current capability: 10KA/5KA/3KA
- Non-Radioactive
- Ultra Low capacitance (<1.5pF)
- Lead-free compliant
- RoHS and REACH compliant
- UL 1449 Recognized: E479668
- Size: Φ 8mm*6mm
- Storage and operational temperature: -40~+125 $^{\circ}$ C

Applications

- | | |
|--|--|
| <p>Automotive:</p> <ul style="list-style-type: none"> • On-board chargers • Vehicle charging stations | <p>Others:</p> <ul style="list-style-type: none"> • LED lighting • Power supply • Photovoltaic • Air conditioning |
|--|--|

Part Number Code



Electrical Characteristics

Part Number		DC Spark-over Voltage ¹⁾²⁾ @100V/S	Impulse Spark-over Voltage		Insulation Resistance ³⁾	Capacitance @1MHz	Glow Voltage @10mA	Arc Voltage @1A	AC withstand voltage @5mA 1Min	Life Ratings		
			100V/μS	1KV/μS						Impulse Discharge Current @8/20μS		AC Discharge Current @50Hz 1S
			Max	Max						Nominal ±5 times	Max 1 time	Nominal 5 times
DIP	SMD	V	V	V	GΩ	pF	V	V	V	KA	KA	A
2R1000T-8	2R1000S-8	1000±20%	1600	1800	1	1.5	160	15	500	10	15	10
2R1200T-8 ⁴⁾	2R1200S-8 ⁴⁾	1200±20%	1800	2000	1	1.5	160	15	600	10	15	10
2R1400T-8	2R1400S-8	1400±20%	2200	2400	1	1.5	235	18	700	5	10	5
2R1500T-8 ⁴⁾	2R1500S-8 ⁴⁾	1500±20%	2300	2500	1	1.5	235	18	750	5	10	5
2R1600T-8	2R1600S-8	1600±20%	2400	2600	1	1.5	235	18	800	5	10	5
2R1800T-8 ⁴⁾	2R1800S-8 ⁴⁾	1800±20%	2600	2800	1	1.5	235	18	900	5	10	5
2R2000T-8	2R2000S-8	2000±20%	2800	3000	1	1.5	260	30	1000	5	10	5
2R2400T-8	2R2400S-8	2400±20%	3200	3400	1	1.5	260	30	1200	5	10	5
2R2500T-8	2R2500S-8	2500±20%	3300	3500	1	1.5	260	30	1300	5	10	5
2R2700T-8	2R2700S-8	2700±20%	3500	3700	1	1.5	260	30	1400	5	10	5
2R3000T-8	2R3000S-8	3000±20%	3700	3900	1	1.5	260	30	1600	5	10	5
2R3500T-8	2R3500S-8	3500±20%	4300	4500	1	1.5	260	30	1800	5	10	5
2R3600T-8	2R3600S-8	3600±20%	4400	4600	1	1.5	260	30	1900	5	10	5
2R4000T-8	2R4000S-8	4000±20%	5000	5500	1	1.5	280	35	2100	3	5	3
2R4500T-8	2R4500S-8	4500±20%	5500	6000	1	1.5	280	35	2300	3	5	3
2R5000T-8	2R5000S-8	5000±20%	6000	6500	1	1.5	280	35	2600	3	5	3

Glow to Arc transition Current..... ~0.5A

Weight.....
 DIP ~1.2g
 SMD ~0.95g

Operation and storage temperature..... -40~+125°C

Climatic category (IEC 60068-1)..... 40/125/21

Marking, red negative..... **RUILON XXX Y**
 XXX -Nominal voltage
 Y -Year of production

Surface treatment.....
 DIP -Nickel Plated
 SMD -Matte-tin plated

¹⁾ At delivery AQL 0.65 level II, DIN ISO 2859.

²⁾ In ionized mode.

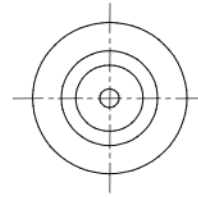
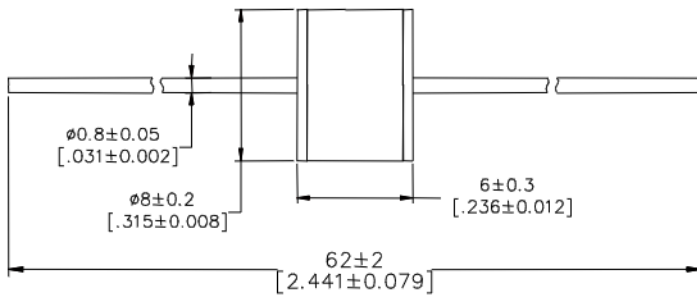
³⁾ Insulation Resistance Measuring Voltage at DC 100V.

⁴⁾ No UL 1449 Recognized.

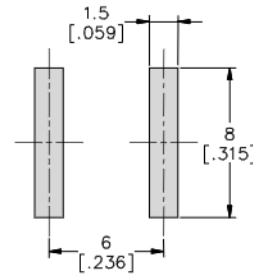
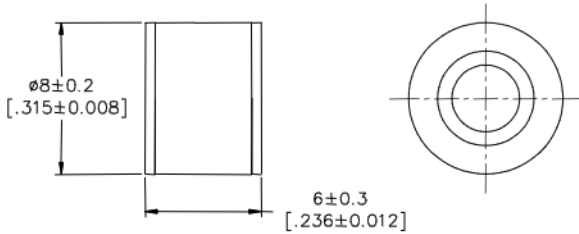
Terms in accordance with ITU-T Rec. K.12, IEC 61643-311, GB/T 9043.

Dimensions (Unit: mm/inch)

DIP Series (2RxxxxT-8)



SMD Series (2RxxxxS-8)

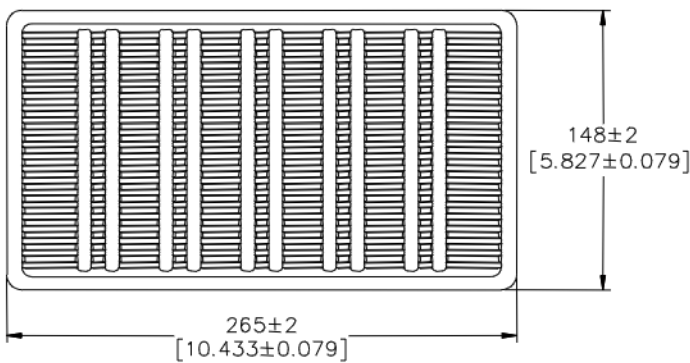


Recommended Soldering Pad Layout

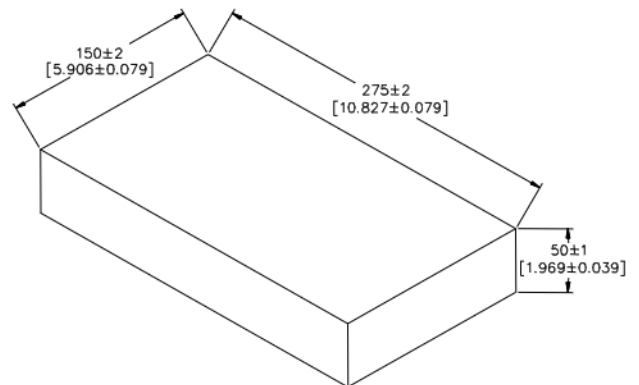
Packaging Information (Unit: mm/inch)

Axial Packaging (Bulk)

Plastic Tray



Inner box



Packaging Quantity:

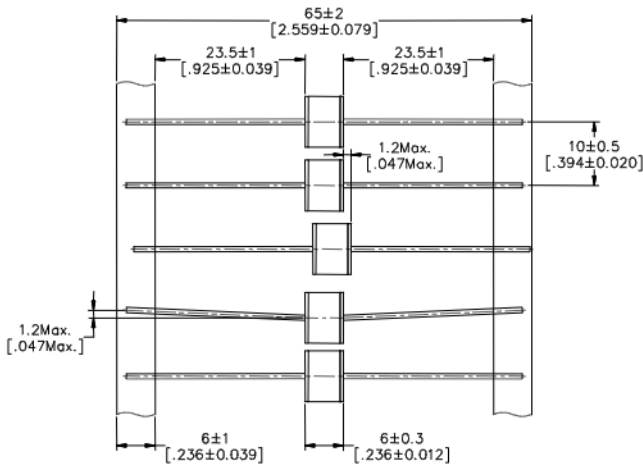
100 PCS per Plastic Tray

5 Plastic Trays per inner box

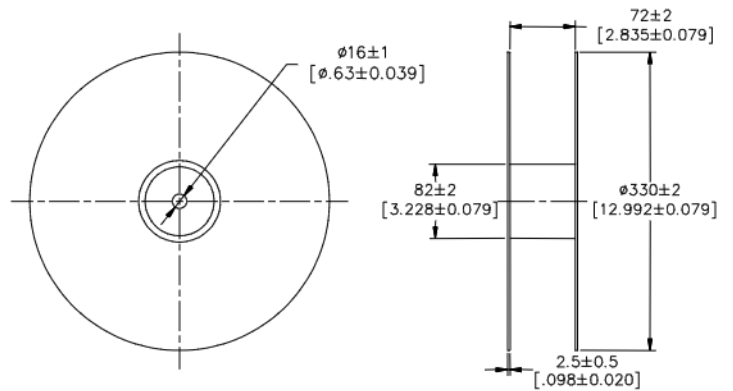
500 PCS per inner box

Axial Packaging (Tape & Reel)

Tape



Reel

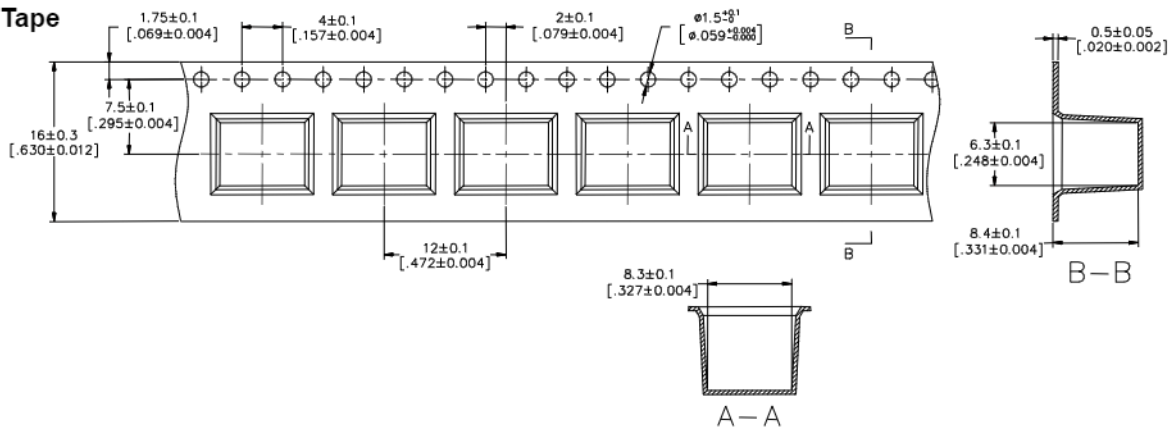


Packaging Quantity:

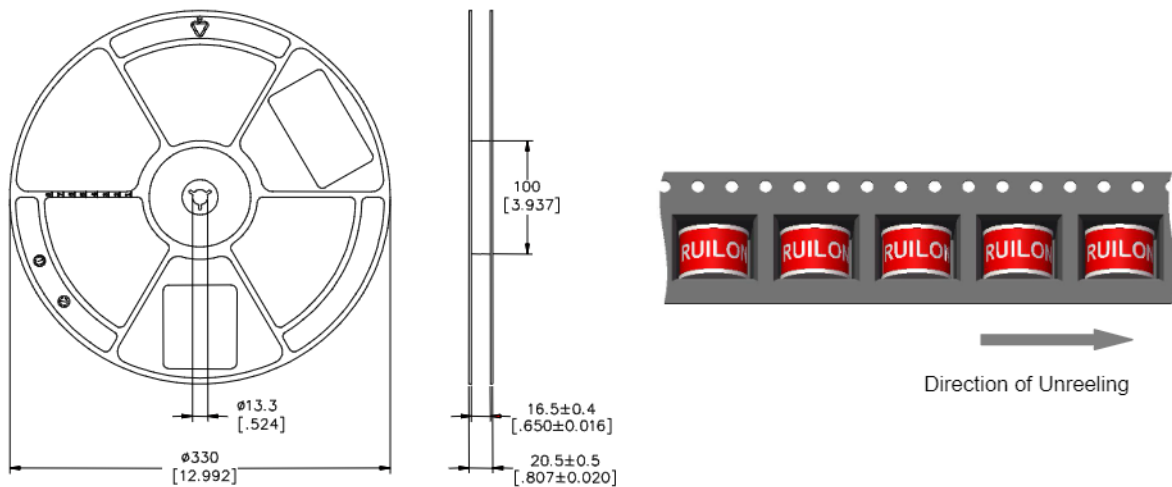
800 PCS per reel

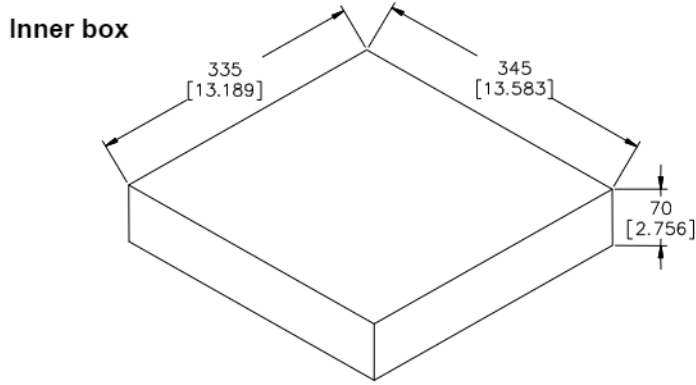
SMD Packaging (Tape & Reel)

Tape



Reel





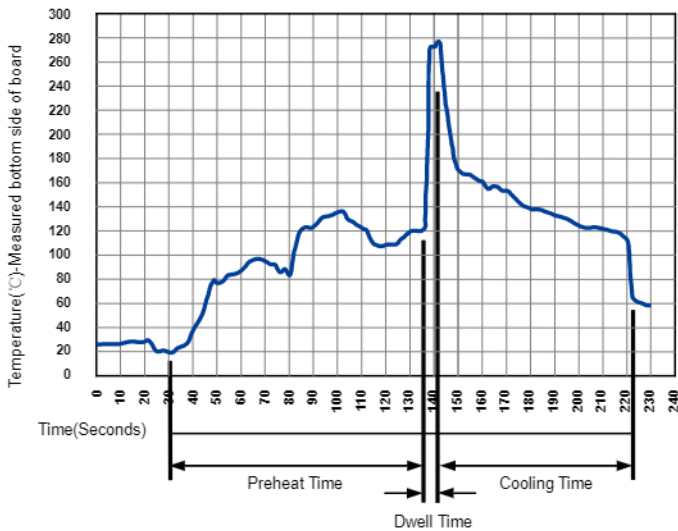
Packaging Quantity:

500 PCS per reel (13")

3 reels per inner box

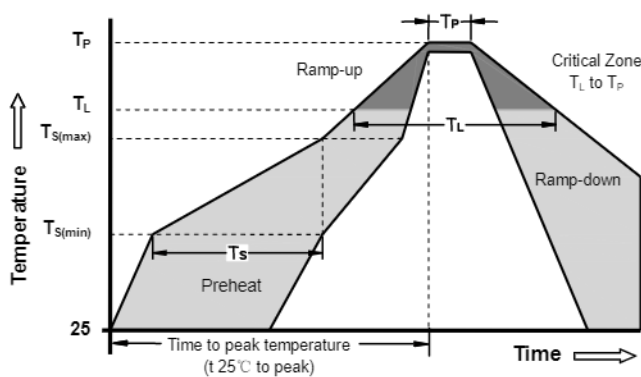
1,500 PCS per inner box

Soldering Parameters - Wave soldering (Thru-Hole Devices)



Wave Soldering Condition		Pb-Free assembly
Preheat	Temperature Min	100°C
	Temperature Max	150°C
	Time (Min to Max)	60-180 Seconds
Solder Pot Temperature		280°C Max
Solder Dwell Time		2-5 Seconds

Soldering Parameters - Reflow Soldering (Surface Mount Devices)



Reflow Condition		Pb - Free assembly
Preheat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 -180 Seconds
Average ramp up rate (Liquids Temp T_L to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquids)	217°C
	- Time (min to max) (t_s)	60 -150 Seconds
Peak Temperature (T_P)		260 +0/-5°C
Time within 5°C of actual peak Temperature (t_p)		10 - 30 Seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max
Do not exceed		260°C